OKI Semiconductor MSM9893L

4M-bit Serial Voice Flash Memory

GENERAL DESCRIPTION

The MSM 9893L is a 4Mb flash memory that operates at 2.7 V to 3.6 V. Since backup is not needed, the number of pins is small, and the chip is contained in a small-package 28-pin TSOP or 30-pin SSOP, the MSM 9893L is a flash memory suitable for applications such as handy terminals. In combination with Oki's recording/playback IC (MSM 9888L/MSM 9889L), a solid-state recording/ playback system can be easily constructed.

FEATURES

 Small page size (one-time write unit) 	: 2,112 bits per page		
 Configuration 	: 2112 bits × 2048 page	es	
• Power supply voltage	: Single 2.7 to 3.6 V		
Operating current	: Supply current : Up	to 35 mA	
	: Stanby current : Up	to 20 μA	
• Operating temperature	e : –10 to +70°C		
Write Cycles	: 10,000 cycles per pag	ge	
Package:			
28-pin plastic TSOP (T	SOPI28-P-813-0.55-K)	(Product name:	MSM9893LTS-KT)
30-pin plastic SSOP (S	SOP30-P-56-0.65-K)	(Product name:	MSM9893ALGS-KT)

PIN CONFIGURATION (TOP VIEW)



NC : No connection

28-Pin Plastic TSOP



NC : No connection

30-Pin Plastic SSOP

PIN DESCRIPTIONS

Pin		0h.s.l		Description		
TSOP	OP SSOP Symbol I/O		I/O			
13	15	DI	I	Command, address, or data input pin.		
14	3	DO	0	Data output pin.		
12	2	SCK	I	Inputs the data transfer clock for the DI and DO pins.		
11	16	CS	I	The device accepts the SCK pulse when \overline{CS} is at "L" level and does not accept the SCK pulse when \overline{CS} is at "H" level.		
1	—	TEST	0	Output pin for test. Leave this pin open.		
3	29	PRT	I	Prohibits flash memory programming at "L" level.		
2	28	RESET	I	The device is reset when RESET is at "L" level.		
6	30	V _{DD}	I	Power supply pin (2.7 to 3.6 V)		
7	1	GND	I	GND pin (0 V)		

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V _{DD}	Ta=25°C	-0.3 to +7.0	V
Input Voltage	V _{IN}	Ta=25°C	-0.6 to V _{DD} +0.6	V
Storage Temperature	T _{STG}	—	–55 to +150	°C

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Range	Unit
Power Supply Voltage	V _{DD}	DGND=AGND=0V	2.7 to 3.6	V
Operating Temperature	T _{op}	—	-10 to +70	°C

ELECTRICAL CHARACTERISTICS

DC Characteristics

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit.
Operating Current	I _{CC}	_	_	15	35	mA
Standby Current	I _{SB}	T _{op} =-10 to +70°C			10	μA
Input Leackage Current	IIL		_	—	1	μA
Output Leackage Current	I _{OL}		_	—	1	μA
Input Low Voltage	VIL		_	_	0.6	V
Input High Voltage	V _{IH}		2.0	_	_	V
Output Low Voltage	V _{OL}			_	0.4	V
Output High Voltage	V _{OH}		2.0	_	_	V

PROGRAMMING/ERASE CHARACTERISTICS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Erase/Programming Cycle	C _{EP}	—	—	—	10,000	Cycles
Data Retention Time	T _{DR}	_			10	Years
Write Disturb *1)	C _{PD}	Bit error : non			20,000	Cycles
		Bit error : 1bit			50,000	Cycles
		Bit error : 3bits	_		100,000	Cycles

*1) "Write Disturb" means a phenomenon that frequent write cycles executed to pages in Flash memory may cause a data error in another page to which write operations are not performed.

For example, 20,001 to 50,000 write operations performed to pages other than page "n" may cause a 1-bit error in page "n".

APPLICATION CIRCUIT



WRITE DISTURB

"Write Distrub" means a phenomenon that the change from digital "0" to "1" may occur in a Flash memory page to which data is scarcely written.

The above change can be avoided by refreshing Flash memory data with the DTRW command and WEND command of the MSM9888L/MSM9889L.

1 DTRW command

2 WEND command

Flash memory.

This command moves some Flash memory page data to buffer.





This command programs buffer data to

TIMING WHEN POWER IS ON

Refer to the MSM9888L/MSM9889L Data Sheet. If the timing diagrams described in the MSM9888L/MSM9889L Data Sheet are not satisfied, errors such as "Recording is disabled" or "Recorded message is erased" may occur.

PACKAGE DIMENSIONS

(Unit : mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, TQFP, LQFP, SOJ, QFJ (PLCC), SHP, and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person on the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

(Unit : mm)



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